

**WSF50N10** 

**N-Ch MOSFET** 

#### **General Description**

The WSF50N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF50N10 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

## **Product Summery**

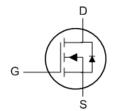
BV <sub>DSS</sub>		I <sub>D</sub>
100V	22mΩ	50A

#### Applications

- High Frequency Point-of-Load Synchronous
  Buck Converter
- Networking DC-DC Power System
- Load Switch

### **TO-252 Pin Configuration**





Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage 100		V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	А
I₀@T₀=100°℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	25	А
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	6.7	A
I <sub>D</sub> @T <sub>A</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.3	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> 160		А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	81	mJ
I <sub>AS</sub>	Avalanche Current	18	A
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	83	W
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup> 33		W
T <sub>STG</sub>	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>eja</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		50	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		1.5	°C/W

## **Absolute Maximum Ratings**



**N-Ch MOSFET** 

#### Electrical Characteristics (T<sub>J</sub>=25<sup>-1</sup>C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , I <sub>D</sub> =250uA	100			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!{\rm C}$ , I_D=1mA		0.098		V/℃
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		22	28	0
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		24	32	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.0	2.0	3.0	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_{D}=250$ uA		-5.52		mV/℃
		V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			10	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			100	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		25.7		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0	1.2	Ω
Qg	Total Gate Charge (10V)			50	65	
Q <sub>gs</sub>	Gate-Source Charge			8	14	nC
Q <sub>gd</sub>	Gate-Drain Charge			10	18	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V,I <sub>D</sub> =20A		18	33	
Tr	Rise Time			9	17	
T <sub>d(off)</sub>	Turn-Off Delay Time			56	101	ns
T <sub>f</sub>	Fall Time			14	26	
Ciss	Input Capacitance			2450		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =30V , V <sub>GS</sub> =0V , f=1MHz		150		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			85		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy⁵	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =18A	80			mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	$V_G = V_D = 0V$ , Force Current			20	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				45	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =20A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	lF=20A , dl/dt=100A/µs , Tյ=25℃		40		nS
Qrr	Reverse Recovery Charge			83		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, \text{L=}0.1\text{mH}, \text{I}_{\text{AS}}\text{=}18\text{A}$ 

4.The power dissipation is limited by 150  $^\circ\!\!\!\mathrm{C}$  junction temperature

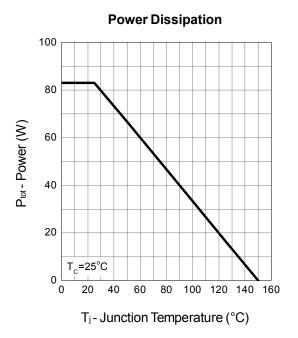
5. The Min. value is 100% EAS tested guarantee.

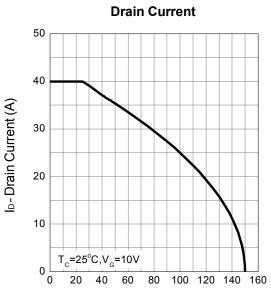
6. The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



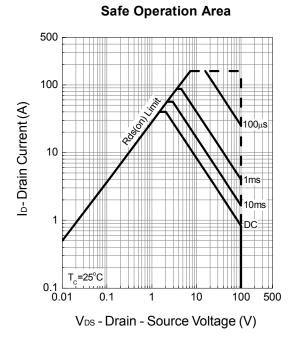
#### **N-Ch MOSFET**

# **Typical Characteristics**

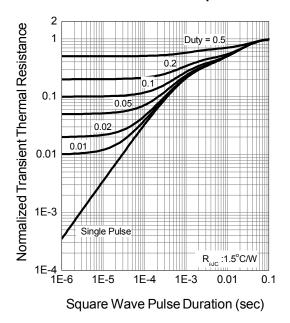




T<sub>j</sub> - Junction Temperature



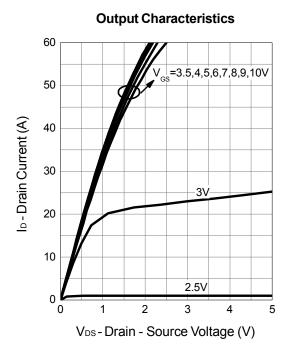
**Thermal Transient Impedance** 



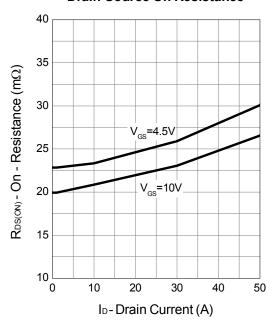


**N-Ch MOSFET** 

## **Typical Characteristics**



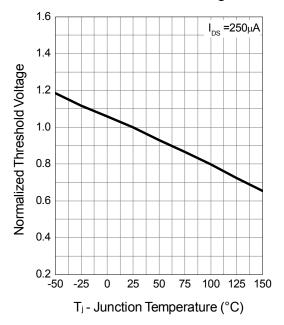
Drain-Source On Resistance



36 I<sub>DS</sub>=20A 33 R<sub>DS(ON)</sub> - On - Resistance (mΩ) 30 27 24 21 18 └─ 2 3 4 5 6 7 8 9 10 VGS - Gate - Source Voltage (V)

**Gate-Source On Resistance** 

Gate Threshold Voltage





**WSF50N10** 

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# **Typical Characteristics**

4000

3500

3000

2500

2000

1500

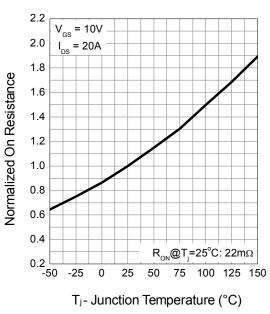
1000

500

0 Crs

8

C - Capacitance (pF)

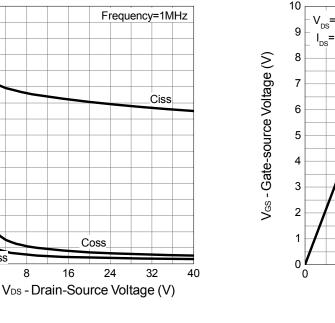


Capacitance

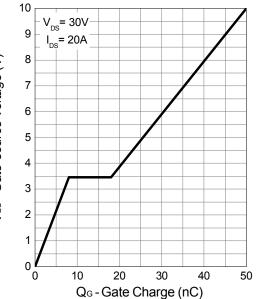
**Drain-Source On Resistance** 

100 T<sub>i</sub>=150°C Is - Source Current (A) 10 T,=25°C 1 0.1 └─ 0.0 0.2 0.6 0.8 1.0 1.2 1.4 0.4 Vsp - Source - Drain Voltage (V)

Source-Drain Diode Forward



**Gate Charge** 





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